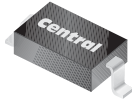


CMDD6001

**SURFACE MOUNT
ULTRA LOW LEAKAGE
SILICON SWITCHING DIODE**

SUPERmini™



SOD-323 CASE



www.centrasemi.com

DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMDD6001 type is a silicon switching diode manufactured by the epitaxial planar process, epoxy molded in a SUPERmini™ surface mount package, designed for switching applications requiring a extremely low leakage diode.

MARKING CODE: C61

MAXIMUM RATINGS: ($T_A=25^{\circ}\text{C}$)

Continuous Reverse Voltage
Peak Repetitive Reverse Voltage
Continuous Forward Current
Peak Repetitive Forward Current
Peak Forward Surge Current, $t_p=1.0\mu\text{s}$
Peak Forward Surge Current, $t_p=1.0\text{s}$
Power Dissipation
Operating and Storage Junction Temperature
Thermal Resistance

SYMBOL

V_R 75
 V_{RRM} 100
 I_F 250
 I_{FRM} 250
 I_{FSM} 4.0
 I_{FSM} 1.0
 P_D 250
 T_J, T_{stg} -65 to +150
 Θ_{JA} 500

UNITS

V
V
mA
mA
A
A
mW
 $^{\circ}\text{C}$
 $^{\circ}\text{C/W}$

ELECTRICAL CHARACTERISTICS: ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I_R	$V_R=75\text{V}$		500	pA
BV_R	$I_R=100\mu\text{A}$	100		V
V_F	$I_F=1.0\text{mA}$		0.85	V
V_F	$I_F=10\text{mA}$		0.95	V
V_F	$I_F=100\text{mA}$		1.1	V
C_T	$V_R=0, f=1.0\text{MHz}$		2.0	pF
t_{rr}	$I_R=I_F=10\text{mA}, I_{rr}=1.0\text{mA}, R_L=100\Omega$		3.0	μs

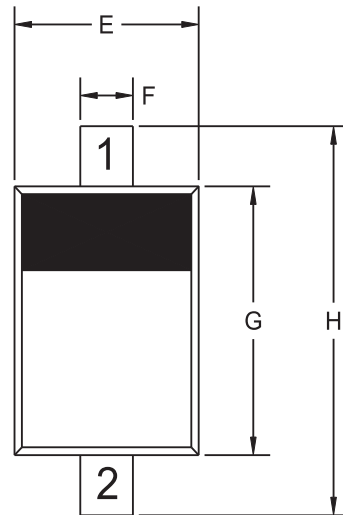
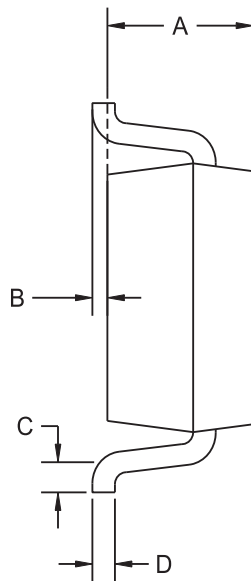
R5 (9-May 2011)

CMDD6001

SURFACE MOUNT
ULTRA LOW LEAKAGE
SILICON SWITCHING DIODE



SOD-323 CASE - MECHANICAL OUTLINE



R4

LEAD CODE:

- 1) Cathode
- 2) Anode

MARKING CODE: C61

SYMBOL	DIMENSIONS			
	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.031	0.039	0.80	1.00
B	0.000	0.004	0.00	0.10
C	0.008	-	0.20	-
D	0.004	0.007	0.11	0.19
E	0.045	0.053	1.15	1.35
F	-	0.014	-	0.35
G	0.063	0.071	1.60	1.80
H	0.094	0.102	2.40	2.60

SOD-323 (REV: R4)

R5 (9-May 2011)

www.centalsemi.com

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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